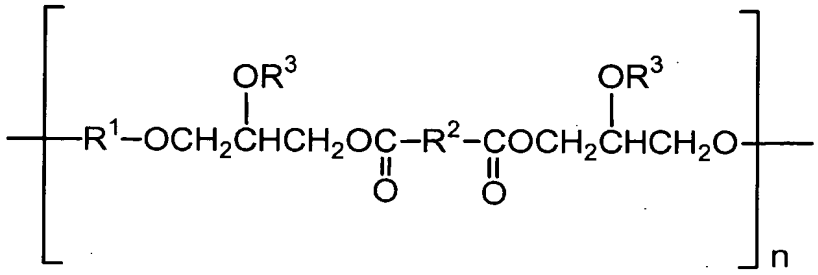
AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Original) A modified epoxy resin containing a repeating unit represented by the following general formula (1):

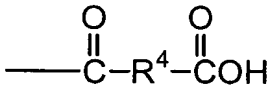
[Chemical Formula 1]



(1)

[wherein R^1 represents a divalent organic group which is a diglycidyl ether-type epoxy compound residue, R^2 represents a divalent organic group which is a dibasic acid residue, R^3 represents a hydrogen atom or a group represented by the following general formula (2):

[Chemical Formula 2]



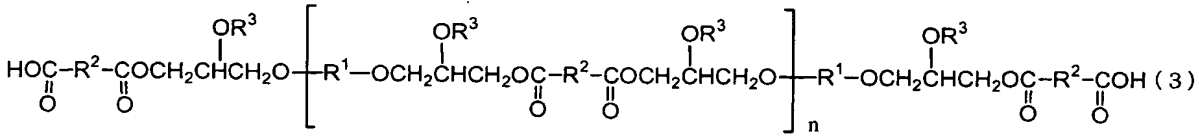
(2)

(wherein R^4 represents an acid anhydride residue),

and n represents an integer of 1 or greater].

2. (Currently amended) A modified epoxy resin represented by the following general formula (3):

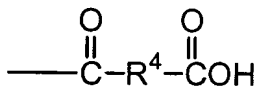
[Chemical Formula 3]



(3)

[wherein R^1 represents a divalent organic group which is a diglycidyl ether-type epoxy compound residue, R^2 represents a divalent organic group which is a dibasic acid residue, R^3 represents a hydrogen atom or a group represented by the following general formula (4)~~(2)~~:

[Chemical Formula 4]



(4)~~(2)~~

(wherein R^4 represents an acid an hydride residue),

and n represents an integer of 1 or greater].

3. (Original) A modified epoxy resin obtained by a production process for a modified epoxy resin which comprises

a first step of obtaining an intermediate product by polymerization reaction between a diglycidyl ether-type epoxy compound and a dibasic acid, and

a second step of adding an acid anhydride to said intermediate product.

4. (Currently amended) A modified epoxy resin according to claim 1 ~~or 3~~, wherein said dibasic acid is a dicarboxylic acid,

and has a linear structure due to ester bonds produced by reaction between carboxyl groups and glycidyl groups in the molecule.

5. (Currently amended) A modified epoxy resin according to claim 1 ~~or 3~~, which has at least one carboxyl group, and has a weight-average molecular weight of 10,000-70,000.

6. (Currently amended) A modified epoxy resin according to claim 1 ~~any one of claims 1 to 4~~, which has a weight-average molecular weight of 10,000-70,000.

7. (Currently amended) A modified epoxy resin according to claim 1 ~~any one of claims 1 to 6~~, which has an acid value of 70-200 mgKOH/g.

8. (Original) A production process for a modified epoxy resin which comprises

a first step of obtaining an intermediate product by polymerization reaction between a diglycidyl ether-type epoxy compound and a dibasic acid, and

a second step of adding an acid anhydride to said intermediate product to obtain a modified epoxy resin.

9. (Original) A production process for a modified epoxy resin according to claim 8, wherein a dicarboxylic acid is used as said dibasic acid.

10. (Currently amended) A production process for a modified epoxy resin according to claim 8 ~~or 9~~, wherein said polymerization reaction in said first step is carried out using a tertiary amine with a pKa of no greater than 9.0 as the catalyst.

11. (Currently amended) A photosensitive resin composition comprising (A) a modified epoxy resin according to claim 1 ~~any one of claims 1 to 7~~, (B) a photopolymerizable compound having at least one ethylenic unsaturated group in the molecule, and (C) a photopolymerization initiator.

12. (Original) A photosensitive resin composition according to claim 11, which further comprises (D) a resin with an unsaturated group, obtained by polymerization of

(a) a resin obtained by copolymerization of a (meth)acrylic acid ester monomer and a monomer with a prescribed functional group (I), and

(b) a compound with a prescribed functional group (II) and an unsaturated group,

by reaction between said functional group (I) and said functional group (II).

13. (Original) A photosensitive resin composition according to claim 12, wherein said functional group (I) is at least one selected from the group consisting of hydroxyl, carboxyl, epoxy and isocyanate.

14. (Original) A photosensitive resin composition according to claim 12, wherein the monomer containing said functional group (I) is at least one selected from the group consisting of 2-hydroxyethyl (meth)acrylate, 2-hydroxypropyl (meth)acrylate, 4-hydroxybutyl (meth)acrylate, phenylglycidylether (meth)acrylate, (meth)acrylic acid, itaconic acid, β-(meth)acryloyloxyethylhydrogen succinate, glycidyl (meth)acrylate, (meth)allylglycidyl ether, vinyl isocyanate, (meth)acryl isocyanate and 2-(meth)acryloyloxyethyl isocyanate.

15. (Currently amended) A photosensitive resin composition according to claim 12~~any one of claims 12 to 14~~, wherein said functional group (II) is at least one selected from the group consisting of aldehyde, hydroxyl, ethyleneimino, carboxyl, epoxy and isocyanate.

16. (Currently amended) A photosensitive resin composition according to claim 12~~any one of claims 12 to 15~~, wherein the unsaturated group of said (b) compound with a prescribed functional group (II) and an unsaturated group is at least one selected from the group consisting of vinyl, isopropenyl, (meth)allyl and (meth)acryloyl.

17. (Currently amended) A photosensitive resin composition according to claim 12~~any one of claims 12 to 16~~, wherein the combination of said functional group (I) and said functional group (II) is a combination selected from the group consisting of

hydroxyl and isocyanate, hydroxyl and epoxy, hydroxyl and aldehyde, hydroxyl and carboxyl, hydroxyl and ethyleneimino, carboxyl and epoxy, carboxyl and hydroxyl, isocyanate and hydroxyl, and epoxy and carboxyl.

18. (Currently amended) A photosensitive resin composition according to claim 12~~any one of claims 12 to 17~~, wherein the glass transition temperature of the (D) resin with an unsaturated group is -10 to 60°C, the weight-average molecular weight is 10,000-200,000 and the acid value is 50-150 mgKOH/g.

19. (Currently amended) A photosensitive resin composition comprising (A) a modified epoxy resin, (B) a photopolymerizable compound having at least one ethylenic unsaturated group in the molecule, and (C) a photopolymerization initiator~~according to any one of claims 11 to 18~~, wherein said component (A) is a modified epoxy resin according to claim 2.

20. (Currently amended) A photosensitive resin composition according to claim 11~~any one of claims 11 to 19~~, which is used to form a flexible cured resin on a film-like base.

21. (Currently amended) A photosensitive resin composition according to claim 11~~any one of claims 11 to 20~~, which is used to form a permanent mask for a flexible printed circuit board.

22. (Currently amended) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 11~~any one of claims 11 to 21~~ formed on said support.

23. (New) A modified epoxy resin according to claim 3, wherein said dibasic acid is a dicarboxylic acid,

and has a linear structure due to ester bonds produced by reaction between carboxyl groups and glycidyl groups in the molecule.

24. (New) A modified epoxy resin according to claim 3, which has at least one carboxyl group, and has a weight-average molecular weight of 10,000-70,000.

25. (New) A modified epoxy resin according to claim 3, which has a weight-average molecular weight of 10,000-70,000.

26. (New) A modified epoxy resin according to claim 3, which has an acid value of 70-200 mgKOH/g.

27. (New) A photosensitive resin composition comprising (A) a modified epoxy resin according to claim 3, (B) a photopolymerizable compound having at least one ethylenic unsaturated group in the molecule, and (C) a photopolymerization initiator.

28. (New) A photosensitive resin composition according to claim 27, which further comprises (D) a resin with an unsaturated group, obtained by polymerization of

(a) a resin obtained by copolymerization of a (meth)acrylic acid ester monomer and a monomer with a prescribed functional group (I), and

(b) a compound with a prescribed functional group (II) and an unsaturated group,

by reaction between said functional group (I) and said functional group (II).

29. (New) A photosensitive resin composition according to claim 28, wherein said component (A) is a modified epoxy resin according to claim 2.

30. (New) A photosensitive resin composition according to claim 27, wherein said component (A) is a modified epoxy resin according to claim 2.

31. (New) A photosensitive resin composition according to claim 12, wherein said component (A) is a modified epoxy resin according to claim 2.

32. (New) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 28 formed on said support.

33. (New) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 27 formed on said support.

34. (New) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 12 formed on said support.